ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	Composition De 2005. IPC, Bannockt and Pan-American co	claration ourn, Illinois. A opyright conve	All rights reserved untions.	nder both	This docume level parts, t	ent is a declarati he declaration e	on of the substand	ces within the m wer level mater	anufacturer ials for whic	listed item. N ch the manufa	Note: if the sector of the sec	he item is an as as engineering	sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
upplier Information													
Company name* Company to			ique ID	le ID Uni			Unique ID Authority			Response Date*			
nsemi									2023-06-08				
Contact Name Title - Cont			ct		Phone - Contact*			I	Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA			1	Product-Env-Stewards@onsemi.com				
Authorized Representative* Title			e - Representative			Phone - Representative*			I	Email - Representative*			
Product-Env-Stewards P			act Enviro Compliance NA Product-Env-Stewards@on				ds@onsemi.co	m					
Requester Item Number			Jumber Mfr Item Name			Effective Date	Version	Manufacturing Site		Weigh	nt*	UOM	Unit Type
	STK544	UC62K-E	3phase inverter H	IC		2023-06-08				13900	.0	mg	Each
Ianufacturing Proccess Inf	ormation					•	-	-				- -	
Terminal Plating / Grid Array Material Terminal I		Cerminal Base	Alloy	J-STD-020 MSI	0 MSL Rating Pe		Peak Process Body Temperature Max Time at Peak		e at Peak To	emperature	Number	of Reflow Cyc	les
Matte Tin (Sn) - annealed		CU Alloy]	NA		0	С	30		seconds	3		
omments													
or more information regarding m	aterial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4678.99	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6	-	58.4874	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		230.6742	mg
			В	Nickel (Ni)	7440-02-0		7.9543	mg
			Supplier	Acrylic resins	Proprietary Data		3.2753	mg
			Supplier	Copper (Cu)	7440-50-8		314.4281	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.3395	mg
			Supplier	Aluminum (Al)	7429-90-5		4061.8313	mg
Chip Parts	49.8	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0149	mg
			Supplier	Silver (Ag)	7440-22-4		2.1812	mg
			Supplier	Epoxy resins	129915-35-1		0.6076	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0299	mg
			Supplier	Tin (Sn)	7440-31-5		1.5787	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.3695	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		8.1074	mg
			Supplier	Phenolic resins	Proprietary Data		0.1444	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0149	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		31.882	mg
			В	Nickel (Ni)	7440-02-0		2.4053	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.1245	mg
			Supplier	Copper (Cu)	7440-50-8		1.3396	mg
Die	29.47	mg	Supplier	Silicon (Si)	7440-21-3		29.47	mg
Die Attach	1.56	mg	Supplier	Silver (Ag)	7440-22-4		1.2012	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2652	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0671	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0265	mg
Lead Frame	788.87	mg	Supplier	Iron (Fe)	7439-89-6		0.71	mg
			Supplier	Copper (Cu)	7440-50-8		788.0023	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1578	mg
Mold Compound-Black	8247.03	mg		Brominated epoxy resin	proprietary data		164.9406	mg
			Supplier	Phenolic Resin	Proprietary Data		494.8218	mg

			Supplier	Epoxy Phenol Resin	Proprietary Data	164.9406	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	247.4109	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	824.7031	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	577.2921	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	5772.9209	mg
Plating	16.97	mg	Supplier	Tin (Sn)	7440-31-5	8.8617	mg
			В	Nickel (Ni)	7440-02-0	8.1083	mg
Solder Ball	43.83	mg	Supplier	Silver (Ag)	7440-22-4	1.3587	mg
			Supplier	Tin (Sn)	7440-31-5	42.1469	mg
			В	Antimony (Sb)	7440-36-0	0.0044	mg
			Supplier	Copper (Cu)	7440-50-8	0.32	mg
Wire Bond	43.48	mg	Supplier	Silicon (Si)	7440-21-3	0.0043	mg
			Supplier	Aluminum (Al)	7429-90-5	43.4757	mg